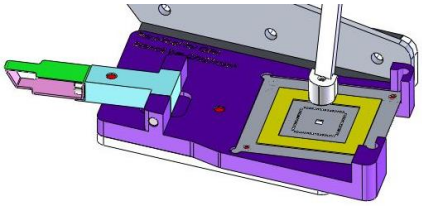
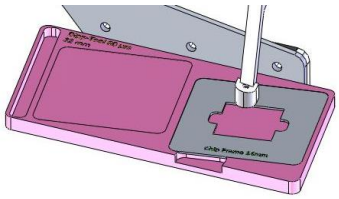
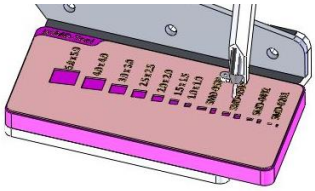
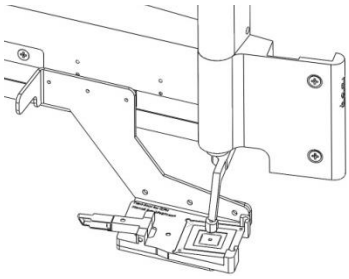
APP Tools

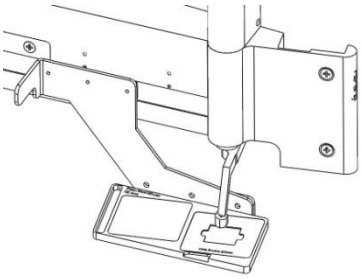
for EXPERT 10.6 Rework Systems

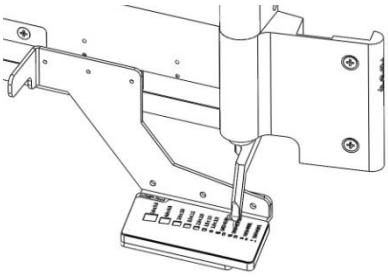












SF64.0520
Print Tool with squeegee

SF64.0525, SF64.0526, SF64.0527
Dip Tool 32 x 0,08 mm with squeegee
Dip Tool 32 x 0,15 mm with squeegee
Dip Tool 32 x 0,22 mm with squeegee

SF64.0540
µSMD Tool

A variety of application tools are available to enable rework of delicate electronic devices. Providing increased automation while simplifying operator requirements results in higher yields and increased process repeatability. Combined with the EXPERT's AVP (Automated Vision Placement) system, innovative application tools reduce overall process times and increase throughput.

Print Tool: This tool is designed to enable QFN and other delicate SMD rework. Using a stencil type fixture, solder paste or paste flux can be applied directly to a component's interconnects. Once printed, an operator secures the Print-Tool housing the printed component to the EXPERT's Process Shuttle. The AVP picks a printed component from the pre-positioned Print Tool and aligns the component to prepared pads of the rework site, hands free. Reworking a QFN with the Print Tool becomes similar to typical BGAs.

Dip Tool: The application of solder flux or solder paste is simplified using the Dip Tool. A defined quantity of flux or solder paste is precisely applied to the component by the system. The SMD is loaded onto a Component Nest supported by the Process Shuttle. Once picked by the system, the component is then dipped into and removed from the Dip-Tool, aligned and then placed by AVP to prepared pads of the rework site, hands free.

µSMD Tool: Even the smallest SMD component is now able to be handled with the EXPERT 10.6 rework system when using the µSMD Nest. Loading of small components can even be done off-line. The pre-loaded µSMD Nest is then installed onto the Process Shuttle awaiting pick-up by the system.

Feature Availability

- Application Tools may require component specific tooling such as sliders, masks and frames. Standard tooling is readily available from MARTIN. Also available is custom tooling to meet your rework needs.

Technical Data

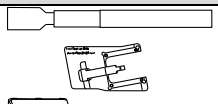
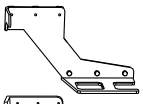
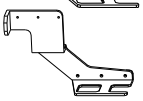
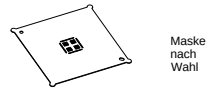
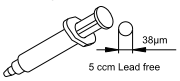
Print-Tool (size range	1,5 x 1,5 mm² - 20 x 120 mm²
Dip-Tool (size range BGA)	3 x 3 mm² - 27 x 27 mm²
µSMD-Tool (size range	0402 – 5 x 5 mm²

MARTIN GmbH
Argelsrieder Feld 1b
82234 Wessling / Germany

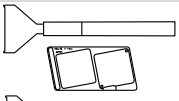
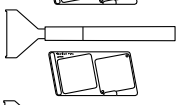
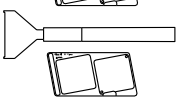
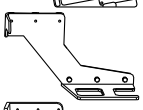
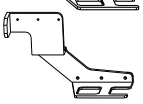
Fon: +49 (0)8153 9329-30
Fax.: +49 (0)8153 9329-39
Web: www.martin-smt.de

APP Tools for EXPERT 10.6 Rework Systems

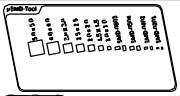
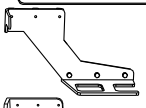
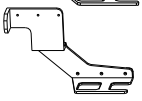
Options and Accessories – PRINT TOOL

SF64.0520	Print tool with squeegee for tool slider	
SF64.0501	Tool slider for AVP 4.1	
SF66.0501	Tool slider for AVP 4.1XL	
LWxx.xx11	Prebumping mask+frame QFN Type of standard QFN mask on request	
VD90.0230	Solder paste print 5ccm finepitch 4 lead free Sn96.5Ag3Cu, ROL0 / 20-38µm	
LW10.0004	Solder paste squeegee for QFN Printer	

Options and Accessories – DIP TOOL

SF64.0525	Dip tool 32x0.08mm with squeegee for tool slider	
SF64.0526	Dip tool 32x0.15mm with squeegee for tool slider	
SF64.0527	Dip tool 32x0.22mm with squeegee for tool slider	
SF64.0501	Tool slider for AVP 4.1	
SF66.0501	Tool slider for AVP 4.1XL	
HT00.0116	Flux Creme lead free 5ccm (appr. 5g), 0506 MA, no clean, REL0	 Lead free
HT00.0117	Flux Creme lead free 100g 0506 MA, no clean, REL0	 100g Leadfree
LW10.0005	Squeegee for dipp tool	

Options and Accessories – µSMD TOOL

SF64.0540	µSMD tool for tool slider	
SF64.0501	Tool slider for AVP 4.1	
SF66.0501	Tool slider for AVP 4.1XL	

Further units and consumables under www.martin-smt.de